

HOSTAFORM® C 27021 XAP® C

HOSTAFORM®

POM copolymer

Easy flow injection molding grade with very low emissions and migrations; designed for consumer packaging.

Emission according to VDA 275 < 2 mg/kg (natural grades)

Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470 FDA = Food and Drug Administration (USA)

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	24 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	1.9 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.8 %	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2900 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	65 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	7.5 %	ISO 527-1/-2
Nominal strain at break	17 %	ISO 527-1/-2
Flexural modulus	2800 MPa	ISO 178
Tensile creep modulus, 1h	2500 MPa	ISO 899-1
Tensile creep modulus, 1000h	1300 MPa	ISO 899-1
Charpy impact strength, 23°C	170 kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	170 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	5.5 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C	5.5 kJ/m ²	ISO 179/1eA
Ball indentation hardness, H 358/30	147 MPa	ISO 2039-1
Poisson's ratio	0.37 ^[C]	

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	106 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110 E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155 W/(m K)	ISO 22007-2
Specific heat capacity of melt	2210 J/(kg K)	ISO 22007-4

Flammability

Burning Behav. at 1.5mm nom. thickn.	HB class	IEC 60695-11-10
Thickness tested	1.5 mm	IEC 60695-11-10
Burning Behav. at thickness h	HB class	IEC 60695-11-10
Thickness tested	3 mm	IEC 60695-11-10
UL recognition	yes	UL 94

HOSTAFORM® C 27021 XAP® C

HOSTAFORM®

Electrical properties

Relative permittivity, 100Hz	4	IEC 62631-2-1
Relative permittivity, 1MHz	4	IEC 62631-2-1
Dissipation factor, 100Hz	25 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50 E-4	IEC 62631-2-1
Volume resistivity	1E12 Ohm.m	IEC 62631-3-1
Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	35 kV/mm	IEC 60243-1
Comparative tracking index	600	IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m ³	ISO 1183

Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa
Ejection temperature	140 °C

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low emissions

Additional information

Injection molding

Preprocessing

To achieve low emission values pre drying using a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

Processing

HOSTAFORM® C 27021 XAP® C

HOSTAFORM®

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

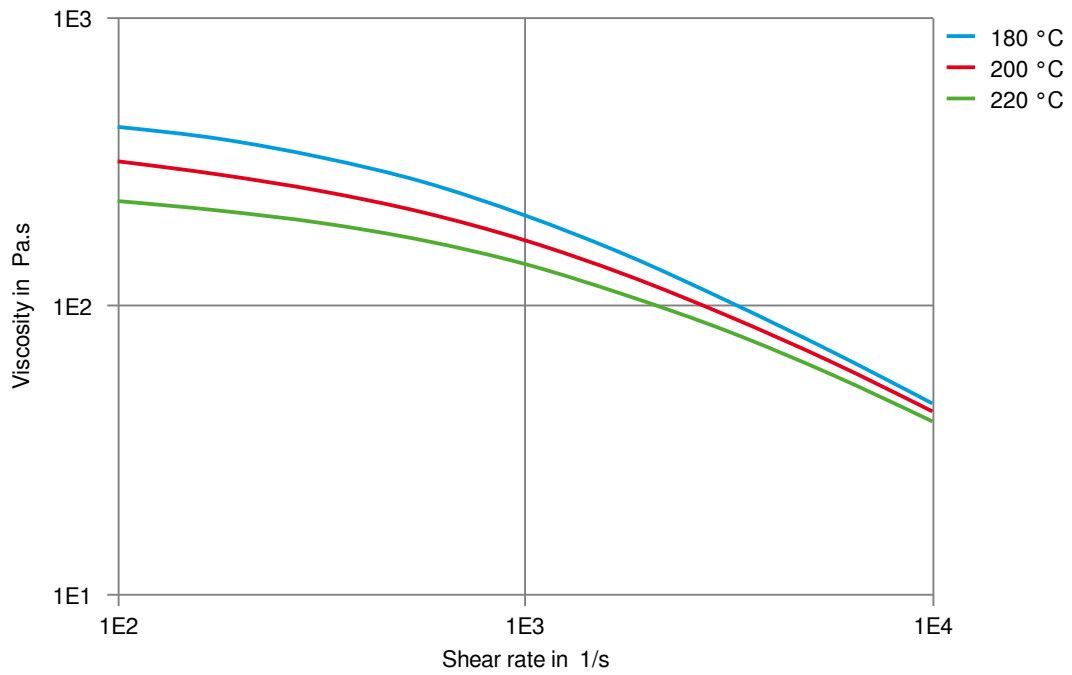
Storage

The product can then be stored in standard conditions until processed.

HOSTAFORM® C 27021 XAP® C

HOSTAFORM®

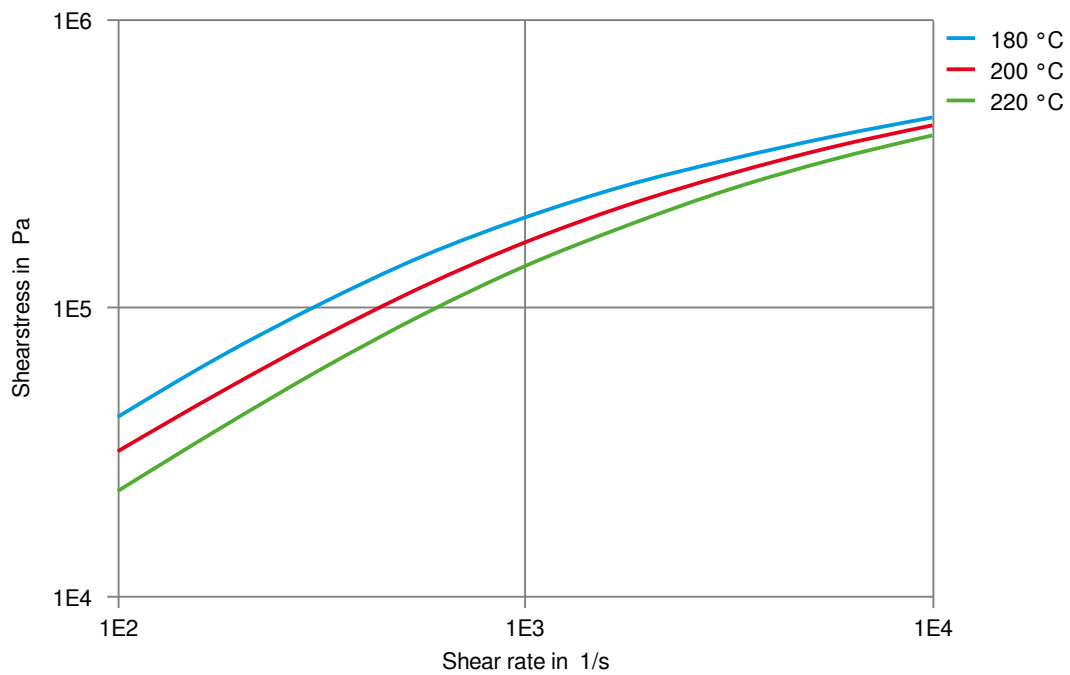
Viscosity-shear rate



HOSTAFORM® C 27021 XAP® C

HOSTAFORM®

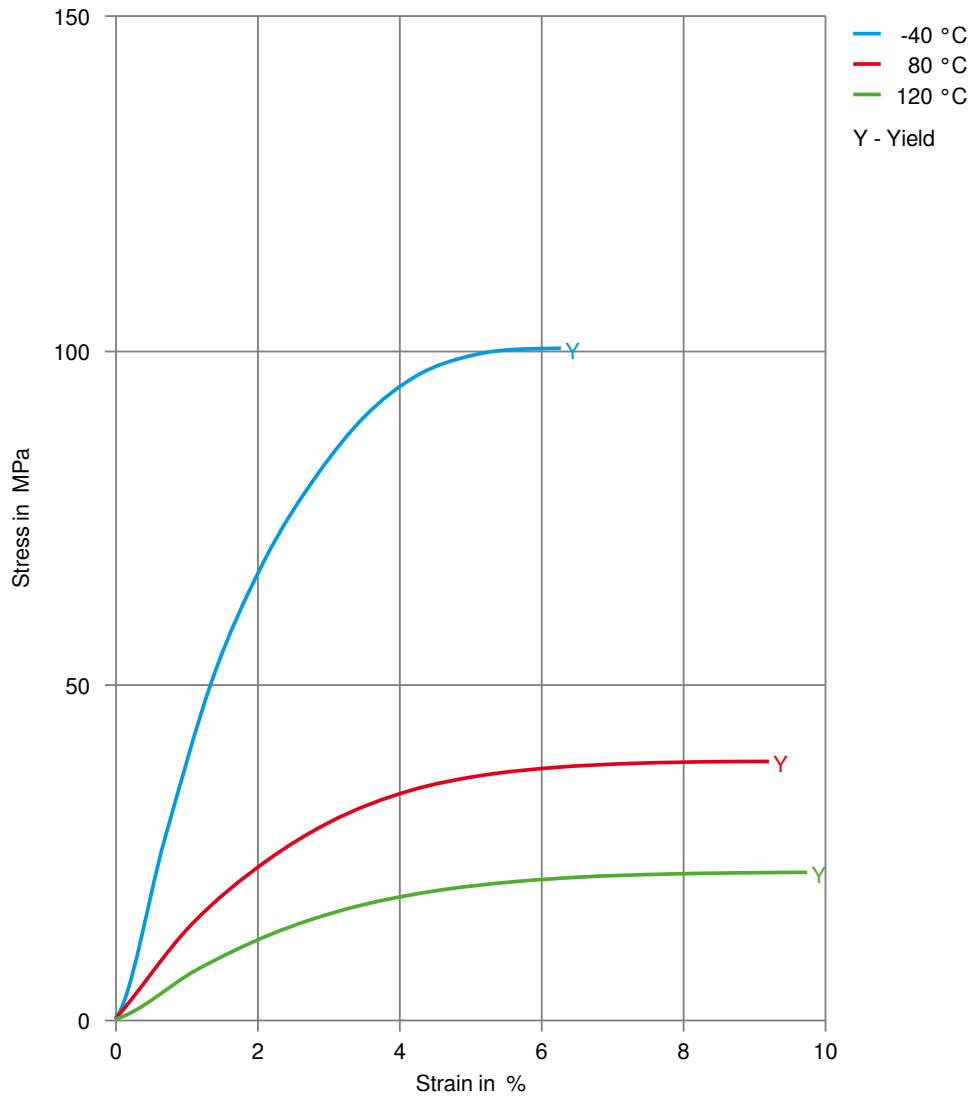
Shearstress-shear rate



HOSTAFORM® C 27021 XAP® C

HOSTAFORM®

Stress-strain



HOSTAFORM® C 27021 XAP® C

HOSTAFORM®

Secant modulus-strain

